PATENT ABSTRACTS OF JAPAN

(11)Publication number:

(43)Date of publication of application: 02.12.1994

(51)Int.CI.

H01L 23/28 // H01L 23/29

(21)Application number: 05-121667

(71)Applicant:

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(22)Date of filing:

24.05.1993

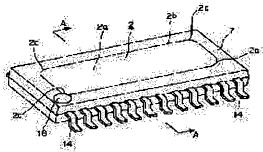
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(54) SEMICONDUCTOR PACKAGE INCORPORATING HEAD SPREADER

PURPOSE: To protect the mold resin against crack in the vicinity of corner part on the peripheral face of a heat spreader.

CONSTITUTION: An IC chip is bonded to one side of a heat spreader 2 in a package and a lead frame 14 is also bonded while keeping insulation and then the IC chip is wire bonded to the lead frame 14. It is then subjected entirely to transfer molding of mold resin 7 while exposing the other surface 2a of the heat spreader 2. Each corner part of the peripheral surface 2a of the heat spreader 2 covered with the mold resin 7 is rounded. This structure restrains concentration of stress due to the difference of thermal expansion coefficient between the heat spreader 2 and the mold resin 7 in the vicinity of each corner part 2c when the temperature drops thus suppressing the occurrence of crack.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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